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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI
Peripherals	LCD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	176 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC (24.23x24.23)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc924-04i-l

TABLE 1-1: PIC16C9XX FAMILY OF DEVICES

		PIC16C923	PIC16C924
Clock	Maximum Frequency of Operation (MHz)	8	8
Memory	EPROM Program Memory	4K	4K
	Data Memory (bytes)	176	176
Peripherals	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/PWM Module(s)	1	1
	Serial Port(s) (SPI/I^2C, USART)	SPI/I^2C	SPI/I^2C
	Parallel Slave Port	—	—
	A/D Converter (8-bit) Channels	—	5
	LCD Module	4 Com, 32 Seg	4 Com, 32 Seg
Features	Interrupt Sources	8	9
	I/O Pins	25	25
	Input Pins	27	27
	Voltage Range (Volts)	2.5-6.0	2.5-6.0
	In-Circuit Serial Programming	Yes	Yes
	Brown-out Reset	—	—
	Packages	64-pin SDIP, TQFP; 68-pin PLCC, Die	64-pin SDIP, TQFP; 68-pin PLCC, Die

All PICmicro Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C9XX Family devices use serial programming with clock pin RB6 and data pin RB7.

4.2.2.3 INTCON REGISTER

The INTCON Register is a readable and writable register which contains various enable and flag bits for the TMR0 register overflow, RB Port change and external RB0/INT pin interrupts.

Note: Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>).

FIGURE 4-5: INTCON REGISTER (ADDRESS 0Bh, 8Bh, 10Bh, 18Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **GIE:** Global Interrupt Enable bit
1 = Enables all un-masked interrupts
0 = Disables all interrupts

bit 6: **PEIE**: Peripheral Interrupt Enable bit
1 = Enables all un-masked peripheral interrupts
0 = Disables all peripheral interrupts

bit 5: **T0IE**: TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 interrupt
0 = Disables the TMR0 interrupt

bit 4: **INTE**: RB0/INT External Interrupt Enable bit
1 = Enables the RB0/INT external interrupt
0 = Disables the RB0/INT external interrupt

bit 3: **RBIE**: RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2: **T0IF**: TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1: **INTF**: RB0/INT External Interrupt Flag bit
1 = The RB0/INT external interrupt occurred (must be cleared in software)
0 = The RB0/INT external interrupt did not occur

bit 0: **RBIF**: RB Port Change Interrupt Flag bit
1 = At least one of the RB7:RB4 pins changed state (see Section 5.2 to clear interrupt)
0 = None of the RB7:RB4 pins have changed state

Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

11.0 SYNCHRONOUS SERIAL PORT (SSP) MODULE

The Synchronous Serial Port (SSP) module is a serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, A/D converters, etc. The SSP module can operate in one of two modes:

- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I^2C)

Refer to Application Note AN578, *"Use of the SSP Module in the I^2C Multi-Master Environment."*

FIGURE 11-1: SSPSTAT: SYNC SERIAL PORT STATUS REGISTER (ADDRESS 94h)

R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0
SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n =Value at POR reset

bit 7: **SMP:** SPI data input sample phase
SPI Master Mode
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
SPI Slave Mode
SMP must be cleared when SPI is used in slave mode

bit 6: **CKE**: SPI Clock Edge Select (Figure 11-5, Figure 11-6, and Figure 11-7)
CKP = 0
1 = Data transmitted on rising edge of SCK
0 = Data transmitted on falling edge of SCK
CKP = 1
1 = Data transmitted on falling edge of SCK
0 = Data transmitted on rising edge of SCK

bit 5: **D/$\overline{A}$**: Data/$\overline{Address}$ bit (I^2C mode only)
1 = Indicates that the last byte received or transmitted was data
0 = Indicates that the last byte received or transmitted was address

bit 4: **P**: Stop bit (I^2C mode only. This bit is cleared when the SSP module is disabled, or when the Start bit was detected last)
1 = Indicates that a stop bit has been detected last (this bit is '0' on RESET)
0 = Stop bit was not detected last

bit 3: **S**: Start bit (I^2C mode only. This bit is cleared when the SSP module is disabled, or when the Stop bit was detected last)
1 = Indicates that a start bit has been detected last (this bit is '0' on RESET)
0 = Start bit was not detected last

bit 2: **R/$\overline{W}$**: Read/Write bit information (I^2C mode only)
This bit holds the R/W bit information following the last address match. This bit is only valid from the address match to the next start bit, stop bit, or $\overline{ACK}$ bit.
1 = Read
0 = Write

bit 1: **UA**: Update Address (10-bit I^2C mode only)
1 = Indicates that the user needs to update the address in the SSPADD register
0 = Address does not need to be updated

bit 0: **BF**: Buffer Full Status bit

Receive (SPI and I^2C modes)
1 = Receive complete, SSPBUF is full
0 = Receive not complete, SSPBUF is empty

Transmit (I^2C mode only)
1 = Transmit in progress, SSPBUF is full
0 = Transmit complete, SSPBUF is empty

12.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

This section applies to the PIC16C924 only.

The analog-to-digital (A/D) converter module has five inputs.

The A/D allows conversion of an analog input signal to a corresponding 8-bit digital number (refer to Application Note AN546 for use of A/D Converter). The output of the sample and hold is the input into the converter, which generates the result via successive approximation. The analog reference voltage is software selectable to either the device's AVDD pin or the voltage level on the RA3/AN3/VREF pin. The A/D converter has a unique feature of being able to operate while the device is in SLEEP mode.

To operate in sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The A/D module has three registers. These registers are:

- A/D Result Register (ADRES)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

The ADCON0 register, shown in Figure 12-1, controls the operation of the A/D module. The ADCON1 register, shown in Figure 12-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be a voltage reference) or as digital I/O.

FIGURE 12-1: ADCON0 REGISTER (ADDRESS 1Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	ADON
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7-6: **ADCS1:ADCS0:** A/D Conversion Clock Select bits
00 = FOSC/2
01 = FOSC/8
10 = FOSC/32
11 = FRC (clock derived from an RC oscillation)

bit 5-3: **CHS2:CHS0**: Analog Channel Select bits
000 = channel 0, (RA0/AN0)
001 = channel 1, (RA1/AN1)
010 = channel 2, (RA2/AN2)
011 = channel 3, (RA3/AN3)
100 = channel 4, (RA5/AN4)

bit 2: **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit

If ADON = 1
1 = A/D conversion in progress (setting this bit starts the A/D conversion)
0 = A/D conversion not in progress (This bit is automatically cleared by hardware when the A/D conversion is complete)

bit 1: **Reserved**: Always maintain this bit clear

bit 0: **ADON**: A/D On bit
1 = A/D converter module is operating
0 = A/D converter module is shutoff and consumes no operating current

12.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 12-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), (Figure 12-4). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 10 kΩ.** After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 12-1 may be used. This equation calculates the acquisition time to within 1/2 LSb error (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

EQUATION 12-1: A/D MINIMUM CHARGING TIME

$V_{HOLD} = (V_{REF} - (V_{REF}/512)) \bullet (1 - e^{(-Tc/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$

Given: $V_{HOLD} = (V_{REF}/512)$, for 1/2 LSb resolution

The above equation reduces to:

$T_C = -(51.2\ pF)(1\ k\Omega - R_{SS} + R_S) \ln(1/511)$

Example 12-1 shows the calculation of the minimum required acquisition time (TACQ). This calculation is based on the following system assumptions.

CHOLD = 51.2 pF

Rs = 10 kΩ

1/2 LSb error

VDD = 5V → Rss = 7 kΩ

Temp (system max.) = 50°C

VHOLD = 0 @ t = 0

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

Note 2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

Note 3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

Note 4: After a conversion has completed, a 2.0 TAD delay must complete before acquisition can begin again. During this time the holding capacitor is not connected to the selected A/D input channel.

EXAMPLE 12-1: CALCULATING THE MINIMUM REQUIRED SAMPLE TIME

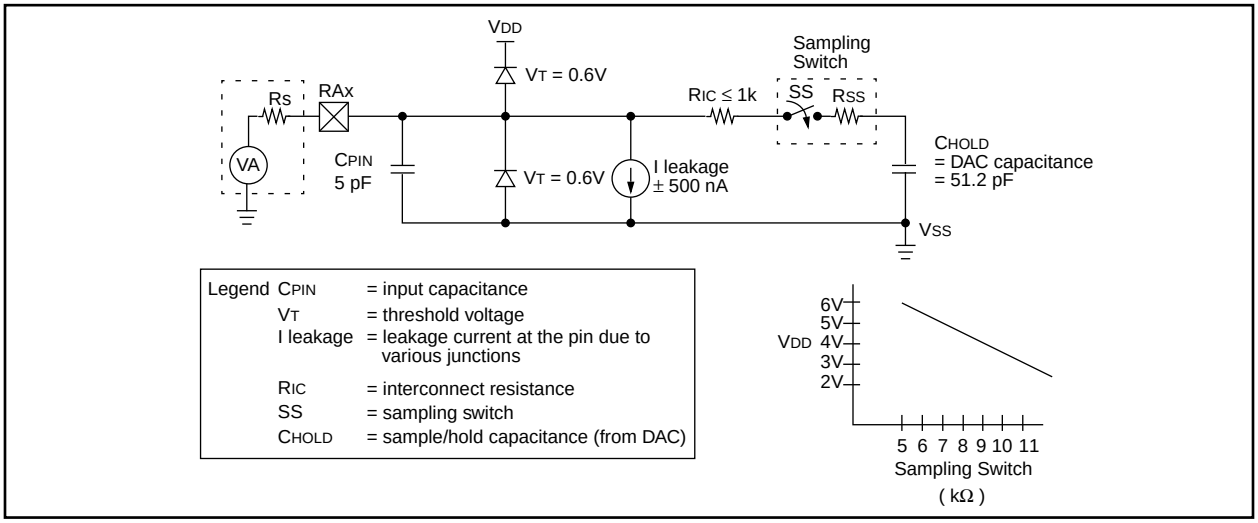
TACQ = Amplifier Settling Time +
Holding Capacitor Charging Time +
Temperature Coefficient

TACQ = 5 µs + Tc + [(Temp - 25°C)(0.05 µs/°C)]

TC = -CHOLD (RIC + RSS + RS) ln(1/511)
-51.2 pF (1 kΩ + 7 kΩ + 10 kΩ) ln(0.0020)
-51.2 pF (18 kΩ) ln(0.0020)
-0.921 µs (-6.2364)
5.747 µs

TACQ = 5 µs + 5.747 µs + [(50°C - 25°C)(0.05 µs/°C)]
10.747 µs + 1.25 µs
11.997 µs

FIGURE 12-4: ANALOG INPUT MODEL



14.2 Oscillator Configurations

14.2.1 OSCILLATOR TYPES

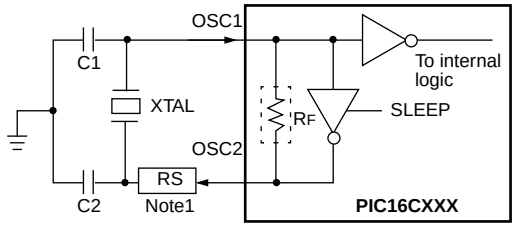
The PIC16CXXX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

14.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 14-2). The PIC16CXXX oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 14-3).

FIGURE 14-2: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



See Table 14-1 and Table 14-2 for recommended values of C1 and C2.

Note 1: A series resistor may be required for AT strip cut crystals.

FIGURE 14-3: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

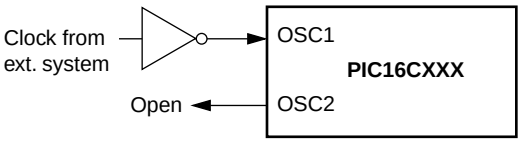


TABLE 14-1: CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq**	**OSC1**	**OSC2**
XT	455 kHz 2.0 MHz 4.0 MHz	68 - 100 pF 15 - 68 pF 15 - 68 pF	68 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz	10 - 68 pF	10 - 68 pF
These values are for design guidance only. See notes at bottom of page.			
Resonators Used:			
455 kHz	Panasonic EFO-A455K04B	± 0.3%	
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%	
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%	
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%	
All resonators used did not have built-in capacitors.			

TABLE 14-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	**Crystal Freq**	**Cap. Range C1**	**Cap. Range C2**
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
These values are for design guidance only. See notes at bottom of page.			
Crystals Used			
32 kHz	Epson C-001R32.768K-A	± 20 PPM	
200 kHz	STD XTL 200.000KHz	± 20 PPM	
1 MHz	ECS ECS-10-13-1	± 50 PPM	
4 MHz	ECS ECS-40-20-1	± 50 PPM	
8 MHz	EPSON CA-301 8.000M-C	± 30 PPM	

Note 1: Recommended values of C1 and C2 are identical to the ranges tested (Table 14-1).
2: Higher capacitance increases the stability of oscillator but also increases the start-up time.
3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
4: Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification.

14.4 Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)

14.4.1 POWER-ON RESET (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.5V - 2.1V). To take advantage of the POR, just tie the $\overline{MCLR}$ pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

For additional information, refer to Application Note AN607, "*Power-up Trouble Shooting*."

14.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only, from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

14.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

14.4.4 TIME-OUT SEQUENCE

On power-up the time-out sequence is as follows: First PWRT time-out is invoked after the POR time delay has expired. Then OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 14-8, Figure 14-9, and Figure 14-10 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if $\overline{MCLR}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{MCLR}$ high will begin execution immediately (Figure 14-9). This is useful for testing purposes or to synchronize more than one PIC16CXXX device operating in parallel.

Table 14-5 shows the reset conditions for some special function registers, while Table 14-6 shows the reset conditions for all the registers.

14.4.5 POWER CONTROL/STATUS REGISTER (PCON)

Bit1 is Power-on Reset Status bit $\overline{POR}$. It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

TABLE 14-3: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Wake-up from SLEEP
	$\overline{PWRTE}$ = 1	$\overline{PWRTE}$ = 0	
XT, HS, LP	1024TOSC	72 ms + 1024TOSC	1024 TOSC
RC	—	72 ms	—

CLRF **Clear f**

Syntax: [*label*] CLRF f

Operands: $0 \le f \le 127$

Operation: $00h \rightarrow (f)$
$1 \rightarrow Z$

Status Affected: Z

Encoding:

00	0001	1fff	ffff

Description: The contents of register 'f' are cleared and the Z bit is set.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write register 'f'

Example

```
CLRF    FLAG_REG
```

Before Instruction
FLAG_REG = 0x5A
After Instruction
FLAG_REG = 0x00
Z = 1

CLRW **Clear W**

Syntax: [*label*] CLRW

Operands: None

Operation: $00h \rightarrow (W)$
$1 \rightarrow Z$

Status Affected: Z

Encoding:

00	0001	0xxx	xxxx

Description: W register is cleared. Zero bit (Z) is set.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No-Operation	Process data	Write to W

Example

```
CLRW
```

Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

INCF **Increment f**

Syntax: [*label*] INCF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (destination)

Status Affected: Z

Encoding:

00	1010	dfff	ffff

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example

```
INCF    CNT, 1
```

Before Instruction
CNT = 0xFF
Z = 0
After Instruction
CNT = 0x00
Z = 1

INCFSZ **Increment f, Skip if 0**

Syntax: [*label*] INCFSZ f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (destination), skip if result = 0

Status Affected: None

Encoding:

00	1111	dfff	ffff

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
If the result is 1, the next instruction is executed. If the result is 0, a NOP is executed instead making it a 2TCY instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

If Skip: (2nd Cycle)

Q1	Q2	Q3	Q4
No-Operation	No-Operation	No-Operation	No-Operation

Example

```
HERE    INCFSZ   CNT, 1
        GOTO     LOOP
CONTINUE •
         •
         •
```

Before Instruction
PC = address HERE
After Instruction
CNT = CNT + 1
if CNT= 0,
PC = address CONTINUE
if CNT≠ 0,
PC = address HERE +1

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Encoding:

00	0000	0xx0	0000

Description: No operation.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No-Operation	No-Operation	No-Operation

Example

```
NOP
```

OPTION **Load Option Register**

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION

Status Affected: None

Encoding:

00	0000	0110	0010

Description: The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.

Words: 1

Cycles: 1

Example

To maintain upward compatibility with future PIC16CXX products, do not use this instruction.

RETFIE **Return from Interrupt**

Syntax: [*label*] RETFIE

Operands: None

Operation: TOS → PC,
1 → GIE

Status Affected: None

Encoding:

00	0000	0000	1001

Description: Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two cycle instruction.

Words: 1

Cycles: 2

Q Cycle Activity:

	Q1	Q2	Q3	Q4
1st Cycle	Decode	No-Operation	Set the GIE bit	Pop from the Stack
2nd Cycle	No-Operation	No-Operation	No-Operation	No-Operation

Example

```
RETFIE
```

After Interrupt
PC = TOS
GIE = 1

RLF **Rotate Left f through Carry**

Syntax: [*label*] RLF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

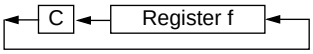
Operation: See description below

Status Affected: C

Encoding:

00	1101	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example

```
RLF     REG1,0
```

Before Instruction
REG1 = 1110 0110
C = 0
After Instruction
REG1 = 1110 0110
W = 1100 1100
C = 1

RRF **Rotate Right f through Carry**

Syntax: [*label*] RRF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

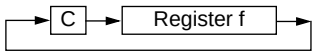
Operation: See description below

Status Affected: C

Encoding:

00	1100	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to destination

Example

```
RRF     REG1,0
```

Before Instruction
REG1 = 1110 0110
C = 0
After Instruction
REG1 = 1110 0110
W = 0111 0011
C = 0

SLEEP

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0011

Description: The power-down status bit, $\overline{PD}$ is cleared. Time-out status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared.
The processor is put into SLEEP mode with the oscillator stopped. See Section 14.8 for more details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No-Operation	No-Operation	Go to Sleep

Example: SLEEP

SUBLW Subtract W from Literal

Syntax: [*label*] SUBLW k

Operands: 0 ≤ k ≤ 255

Operation: k - (W) → (W)

Status Affected: C, DC, Z

Encoding:

11	110x	kkkk	kkkk

Description: The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example 1: SUBLW 0x02

Before Instruction
W = 1
C = ?
Z = ?

After Instruction
W = 1
C = 1; result is positive
Z = 0

Example 2: Before Instruction
W = 2
C = ?
Z = ?

After Instruction
W = 0
C = 1; result is zero
Z = 1

Example 3: Before Instruction
W = 3
C = ?
Z = ?

After Instruction
W = 0xFF
C = 0; result is negative
Z = 0

17.3 DC Characteristics: PIC16C923/924-04 (Commercial, Industrial) PIC16C923/924-08 (Commercial, Industrial) PIC16LC923/924-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec				
Param No.	**Characteristic**	**Sym**	**Min**	**Typ †**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	-	0.15VDD	V	For entire VDD range
			VSS	-	0.8V	V	4.5V ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer		VSS	-	0.2VDD	V	
D032	$\overline{MCLR}$, OSC1 (in RC mode)		VSS	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		VSS	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports	VIH		-			
D040	with TTL buffer		2.0	-	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.8VDD	-	VDD	V	
D042	$\overline{MCLR}$		0.8VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	250	400	µA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1.0	µA	Vss ≤ VPIN ≤ VDD, Pin at hi-Z
D061	$\overline{MCLR}$, RA4/T0CKI		-	-	±5	µA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	VOL	-	-	0.6	V	IOL = 4.0 mA, VDD = 4.5V
D083	OSC2/CLKOUT (RC osc mode)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V
	Output High Voltage						
D090	I/O ports (Note 3)	VOH	VDD - 0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V
D092	OSC2/CLKOUT (RC osc mode)		VDD - 0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V
	Capacitive Loading Specs on Output Pins						
D100*	OSC2 pin	COSC2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101*	All I/O pins and OSC2 (in RC)	CIO	-	-	50	pF	
D102*	SCL, SDA in I^2C mode	CB	-	-	400	pF	
D150*	Open -Drain High Voltage	VDD	-	-	14	V	RA4 pin

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C9XX be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

FIGURE 17-2: LOAD CONDITIONS

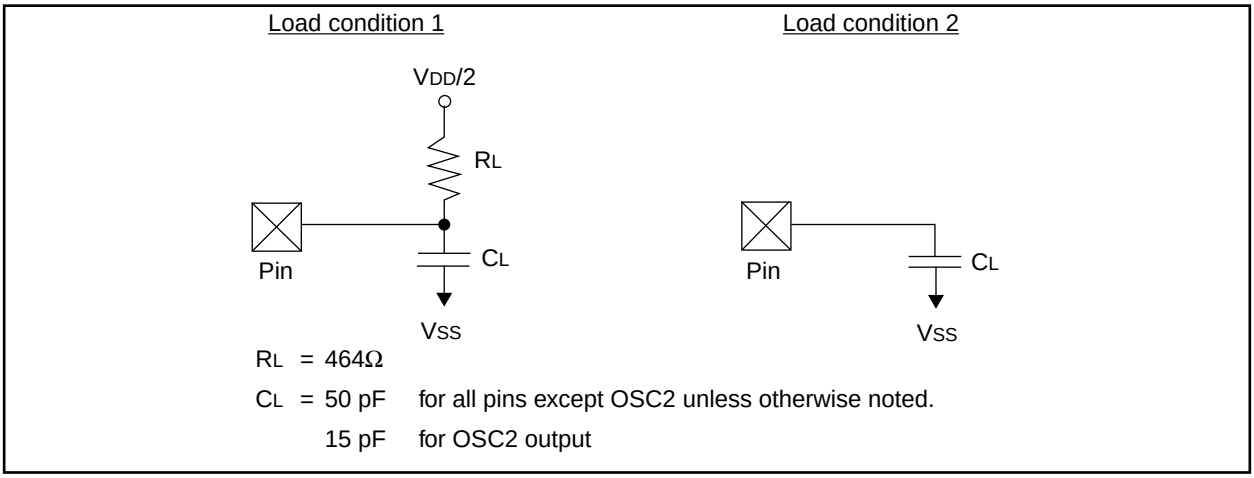
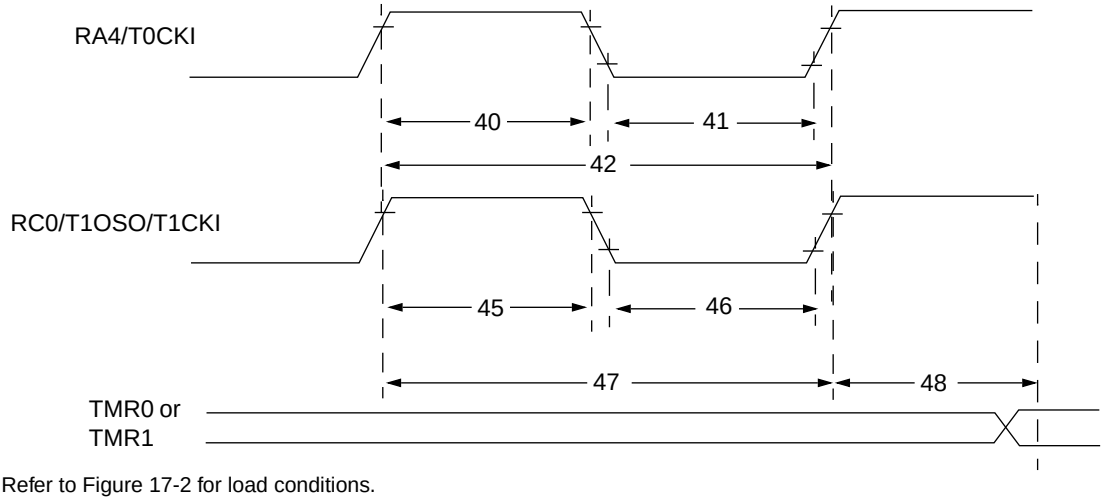


FIGURE 17-6: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS



Refer to Figure 17-2 for load conditions.

TABLE 17-7: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet parameter 42
				With Prescaler	10	—	—	ns	
41*	Tt0L	T0CKI Low Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet parameter 42
				With Prescaler	10	—	—	ns	
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	—	ns	
				With Prescaler	Greater of: 20 or TCY + 40 / N	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	Tt1H	T1CKI High Time	Synchronous, Prescaler = 1		0.5TCY + 20	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	PIC16**C**923/924	15	—	—	ns	
				PIC16**LC**923/924	25	—	—	ns	
			Asynchronous	PIC16**C**923/924	30	—	—	ns	
				PIC16**LC**923/924	50	—	—	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, Prescaler = 1		0.5TCY + 20	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	PIC16**C**923/924	15	—	—	ns	
				PIC16**LC**923/924	25	—	—	ns	
			Asynchronous	PIC16**C**923/924	30	—	—	ns	
				PIC16**LC**923/924	50	—	—	ns	
47*	Tt1P	T1CKI input period	Synchronous	PIC16**C**923/924	Greater of: 30 OR TCY + 40 / N	—	—	ns	N = prescale value (1, 2, 4, 8)
				PIC16**LC**923/924	Greater of: 50 OR TCY + 40 / N				N = prescale value (1, 2, 4, 8)
			Asynchronous	PIC16**C**923/924	60	—	—	ns	
				PIC16**LC**923/924	100	—	—	ns	
	Ft1	Timer1 oscillator input frequency range (oscillator enabled by setting bit T1OSCEN)			DC	—	200	kHz	
48	TCKEZtmr1	Delay from external clock edge to timer increment			2Tosc	—	7Tosc	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 17-9: SPI MODE REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK$\downarrow$ or SCK$\uparrow$ input		TCY	—	—	ns	
71*	TscH	SCK input high time (slave mode)	Continuous	1.25TCY + 30	—	—	ns	
71A*			Single Byte	40	—	—	ns	
72*	TscL	SCK input low time (slave mode)	Continuous	1.25TCY + 30	—	—	ns	
72A*			Single Byte	40				
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		50	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		50	—	—	ns	
75*	TdoR	SDO data output rise time		—	10	25	ns	
76*	TdoF	SDO data output fall time		—	10	25	ns	
77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output hi-impedance		10	—	50	ns	
78*	TscR	SCK output rise time (master mode)		—	10	25	ns	
79*	TscF	SCK output fall time (master mode)		—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge		—	—	50	ns	
81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		TCY	—	—	ns	
82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge		—	—	50	ns	
83*	TscH2ssH, TscL2ssH	$\overline{SS}\uparrow$ after SCK edge		1.5TCY + 40	—	—	ns	
84*	Tb2b	Delay between consecutive bytes		1.5TCY + 40	—	—	ns	

* Characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 18-14:TYPICAL IDD vs. FREQUENCY (RC MODE @ 20 pF, 25°C)

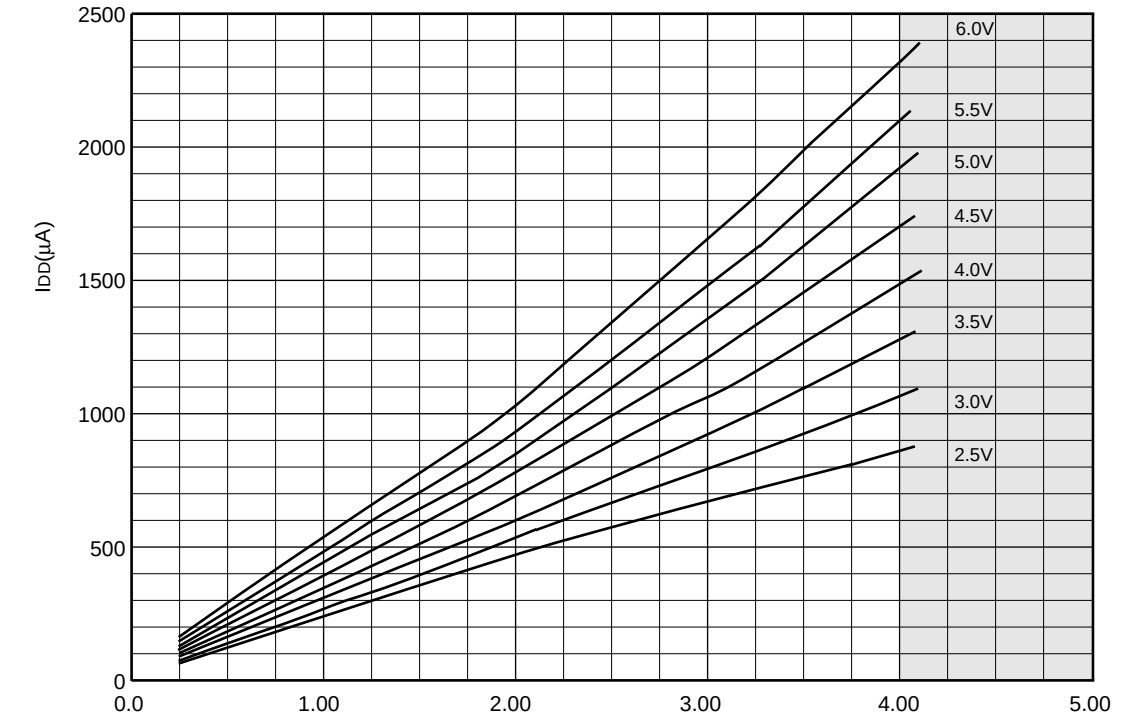
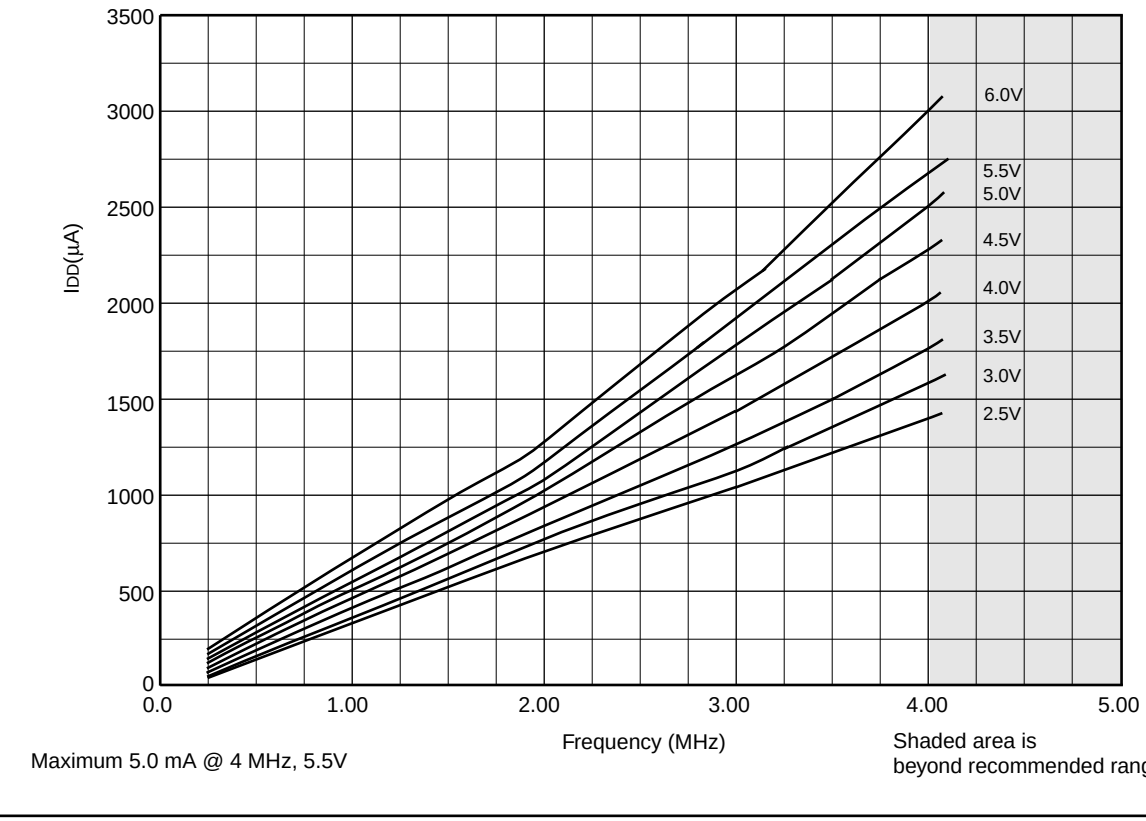


FIGURE 18-15:MAXIMUM IDD vs. FREQUENCY (RC MODE @ 20 pF, -40°C TO +85°C)



Data based on process characterization samples. See first page of this section for details.

FIGURE 18-16:TYPICAL IDD vs. FREQUENCY (RC MODE @ 100 pF, 25°C)

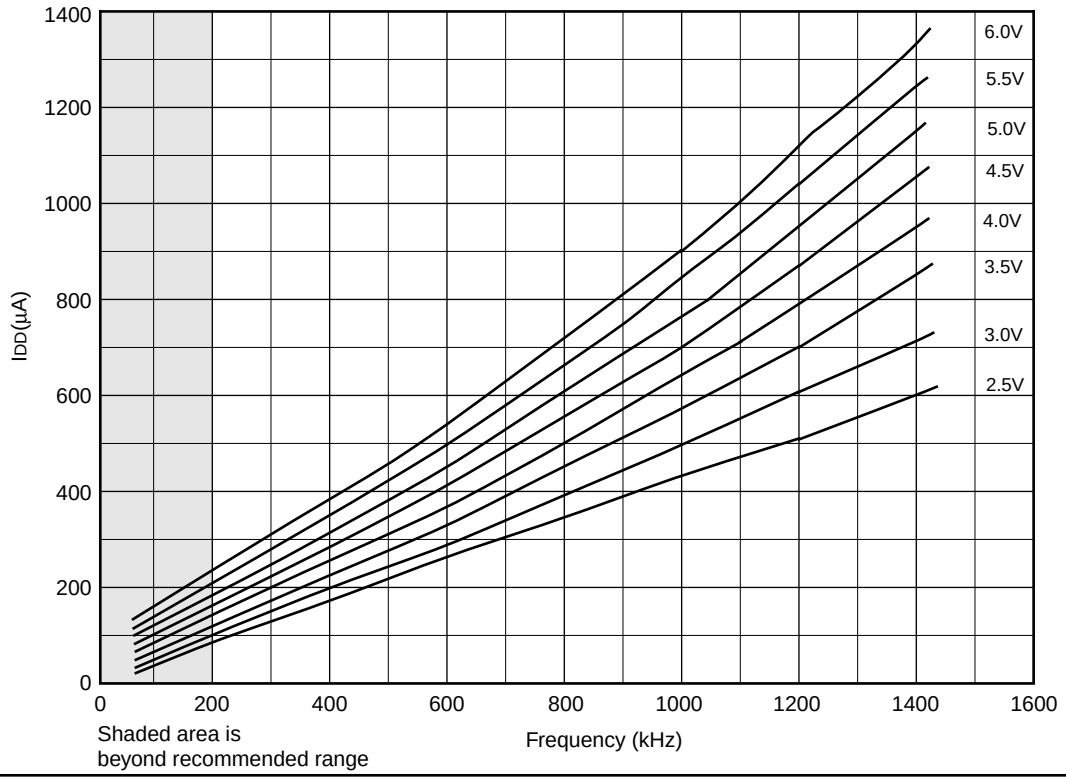
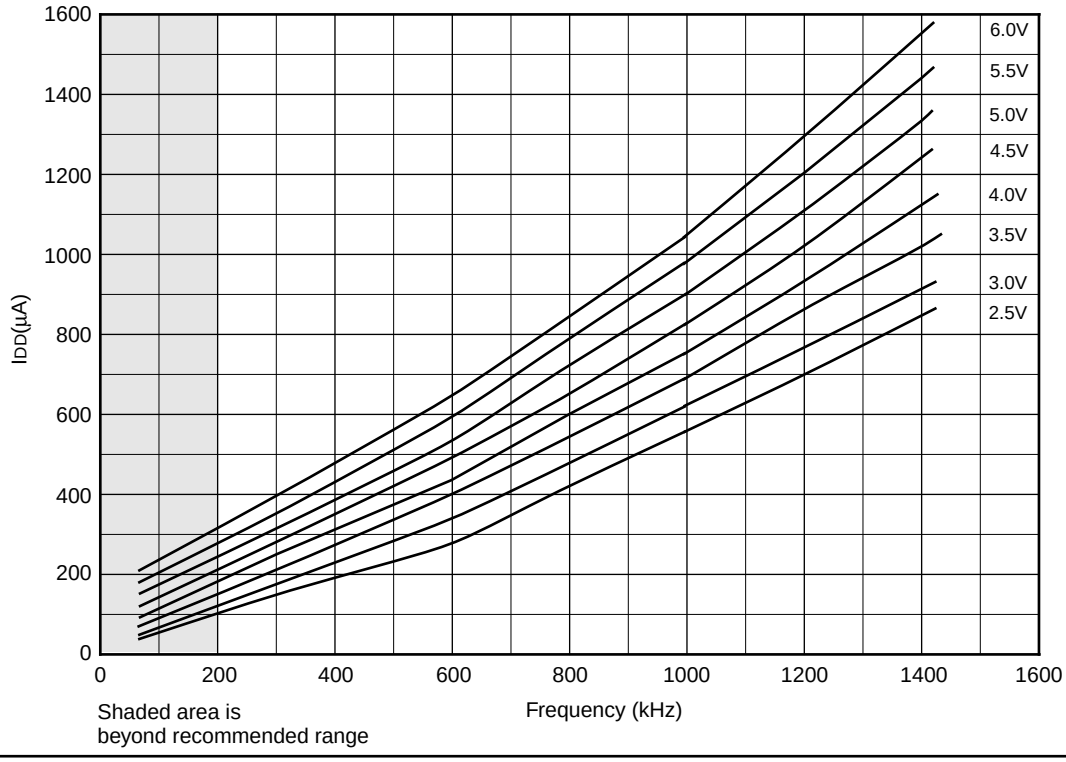


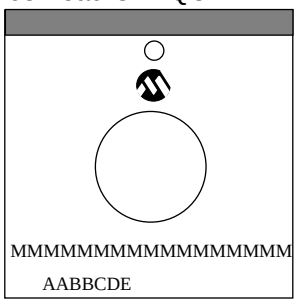
FIGURE 18-17:MAXIMUM IDD vs. FREQUENCY (RC MODE @ 100 pF, -40°C TO +85°C)



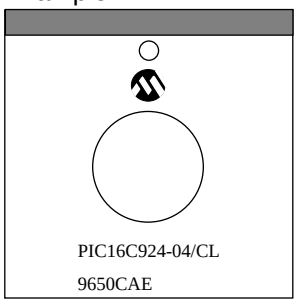
Data based on process characterization samples. See first page of this section for details.

19.4 Package Marking Information

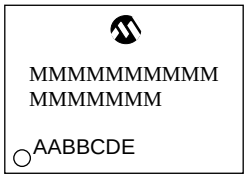
68-Lead CERQUAD Windowed



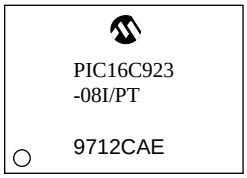
Example



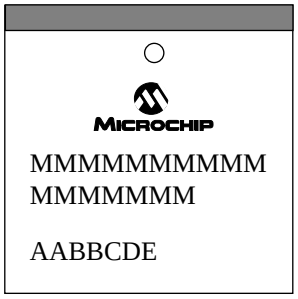
64-Lead TQFP



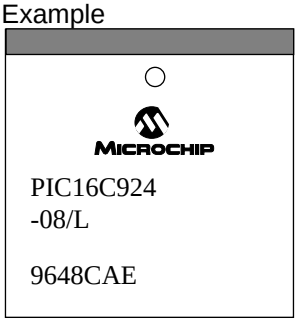
Example



68-Lead PLCC



Example



64-Lead SDIP (Shrink DIP)

Example

Legend:	MM...M	Microchip part number information
	XX...X	Customer specific information*
	AA	Year code (last 2 digits of calender year)
	BB	Week code (week of January 1 is week '01')
	C	Facility code of the plant at which wafer is manufactured. C = Chandler, Arizona, U.S.A. S = Tempe, Arizona, U.S.A.
	D_1	Mask revision number for microcontroller
	E	Assembly code of the plant or country of origin in which part was assembled.
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.	

* Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask revision number, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

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